

**N-CHANNEL SILICON POWER MOS-FET****■ Features**

- High speed switching**
- Low on-resistance**
- No secondary breakdown**
- Low driving power**
- Avalanche-proof**

**■ Applications**

- Switching regulators**
- UPS (Uninterruptible Power Supply)**
- DC-DC converters**

**■ Maximum ratings and characteristic****(T<sub>c</sub>=25°C unless otherwise specified)**

Item	Symbol	Rating	Unit
Drain-source voltage	V <sub>DS</sub>	1000	V
Continuous drain current	I <sub>D</sub>	±7	A
Pulsed drain current	I <sub>D(puls)</sub>	±28	A
Gate-source voltage	V <sub>GS</sub>	±30	V
Repetitive or non-repetitive	I <sub>AR</sub> *2	7	A
Maximum Avalanche Energy	E <sub>AV</sub> *1	463	mJ
Max. power dissipation	P <sub>D</sub>	255	W
Operating and storage temperature range	T <sub>ch</sub>	+150	°C
	T <sub>stg</sub>	-55 to +150	°C

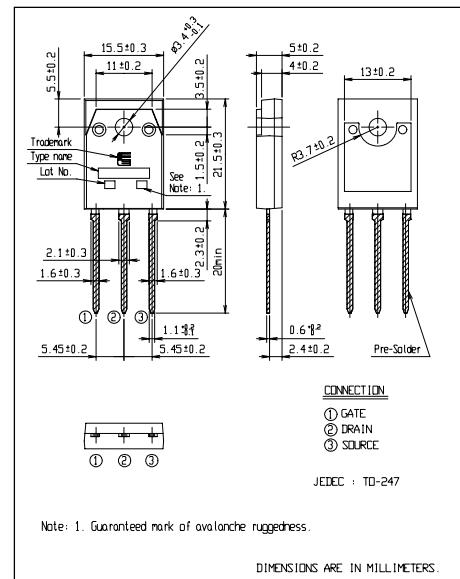
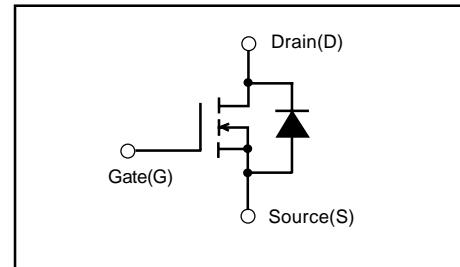
\*1 L=17.3mH, V<sub>cc</sub>=100V   \*2 T<sub>ch</sub>≤150°C

**(T<sub>c</sub>=25°C unless otherwise specified)**

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> =1mA V <sub>GS</sub> =0V	100			V
Gate threshold voltage	V <sub>GS(th)</sub>	I <sub>D</sub> =1mA V <sub>DS</sub> =V <sub>GS</sub>	2.5	3.0	3.5	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =1000V V <sub>GS</sub> =0V	10	500	500	μA
		T <sub>ch</sub> =25°C T <sub>ch</sub> =125°C	0.2	1.0	1.0	mA
Gate-source leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V V <sub>DS</sub> =0V	10	100	100	nA
Drain-source on-state resistance	R <sub>D(S(on))</sub>	I <sub>D</sub> =3.5A V <sub>GS</sub> =10V		1.54	2.0	Ω
Forward transconductance	g <sub>fs</sub>	I <sub>D</sub> =3.5A V <sub>DS</sub> =25V	2.7	5.5		S
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V	1480	2220		pF
Output capacitance	C <sub>oss</sub>	V <sub>GS</sub> =0V	170	255		
Reverse transfer capacitance	C <sub>rss</sub>	f=1MHz	75	113		
Turn-on time t <sub>on</sub>	t <sub>d(on)</sub>	V <sub>CC</sub> =600V I <sub>D</sub> =7A	25	38		ns
	t <sub>r</sub>	V <sub>GS</sub> =10V	50	75		
Turn-off time t <sub>off</sub>	t <sub>d(off)</sub>	R <sub>GS</sub> =10Ω	160	240		
	t <sub>f</sub>		70	105		
Total gate charge	Q <sub>G</sub>	V <sub>CC</sub> =500V	84	126		nC
Gate-Source charge	Q <sub>GS</sub>	I <sub>D</sub> =7A	23	35		
Gate-Drain charge	Q <sub>GD</sub>	V <sub>GS</sub> =10V	31	47		
Avalanche capability	I <sub>AV</sub>	L=17.3 mH T <sub>ch</sub> =25°C	7			A
Diode forward on-voltage	V <sub>SD</sub>	I <sub>F</sub> =2xI <sub>DR</sub> V <sub>GS</sub> =0V T <sub>ch</sub> =25°C		1.00	1.50	V
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> =I <sub>DR</sub> V <sub>GS</sub> =0V		1.6		μs
Reverse recovery charge	Q <sub>rr</sub>	-di/dt=100A/μs T <sub>ch</sub> =25°C		15.0		μC

**■ Thermal characteristics**

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal resistance	R <sub>th(ch-c)</sub>	channel to case			0.490	°C/W
	R <sub>th(ch-a)</sub>	channel to ambient			50.0	°C/W

**■ Equivalent circuit schematic**

## ■ Characteristics

